

Datacon 8800 FC QUANTUM *advX*



Boost your manufacturing process to the next level with the **8800 FC QUANTUM *advX***, our latest innovation in Flip Chip assembly. Designed to deliver extraordinary speed and accuracy, this cutting-edge system is perfect for high-volume production lines.

With a **die size range of 0.3 - 40 mm**, the **8800 FC QUANTUM *advX*** can handle a very wide application range to address all relevant mass reflow C2S applications.

Exceptional **Placement Accuracy of 4 μm**, stretching the limits of small bump size mass reflow applications.



The SUPERIOR Flip Chip Solution

- Throughput up to 10k
- Chip size 0.3 - 40 mm
- 4 μm placement accuracy

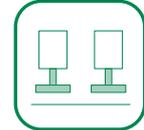
SPEED



SMALLEST FOOTPRINT



DUAL PICK & PLACE



TOOL-TO-TOOL REPEATABILITY



ADVANCED OPTICS



FULL AUTO TOOL TEACH

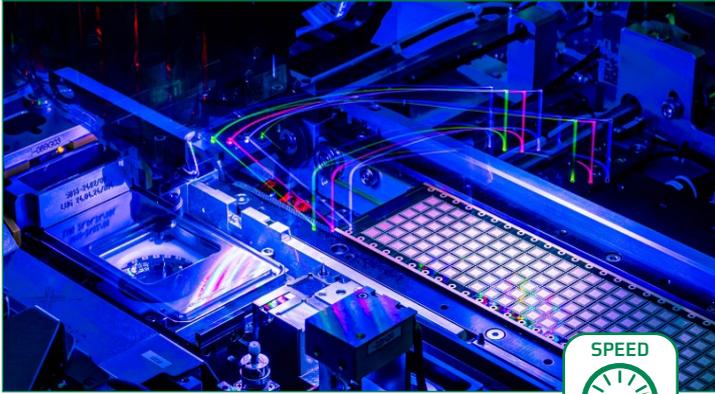


ACCURACY



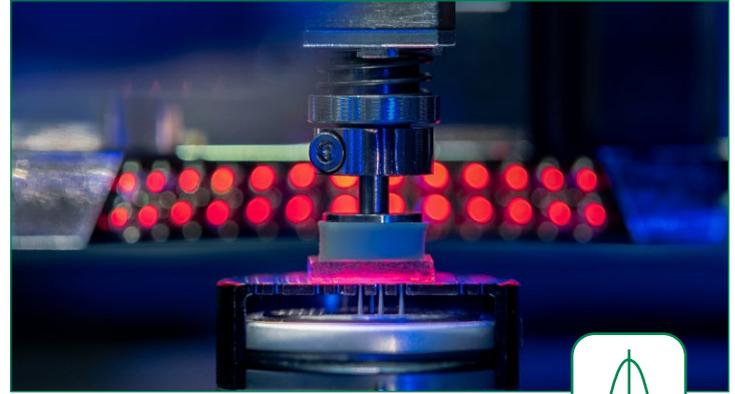
POWER SAVING





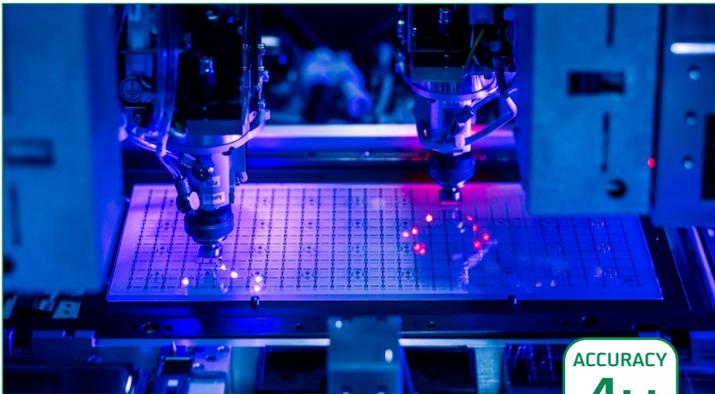
Unprecedented Speed

- Dual gantry system
- Super size CRYSTAL dipping
- Newest BESI vision technology



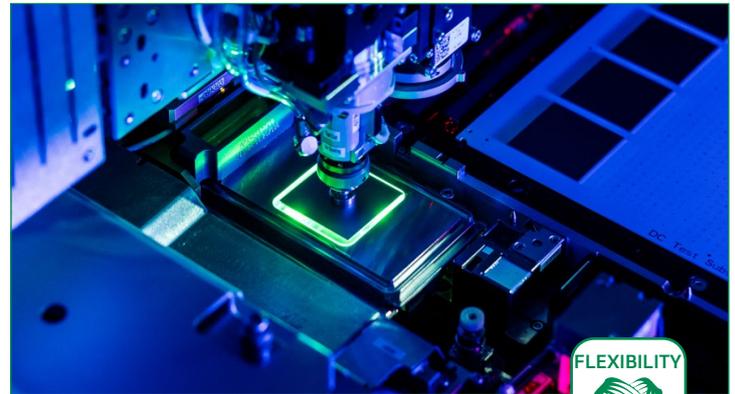
Full Yield Control

- Auto needle height determination
- Flip touchdown monitoring
- Flux depending dipping speed sets



Proven Production Accuracy

- 4 µm at highest speed
- High resolution vision system
- Thermally optimized gantry system



Application Flexibility

- FC-BGA, FC-CSP, DRAM, Fan-out C2W
- Die size up to 40 mm
- Singulated substrates, strips and wafer

Feature	Datacon 8800 FC QUANTUM <i>sigma</i>	Datacon 8800 FC QUANTUM <i>advanced</i>	Datacon 8800 FC QUANTUM <i>h5</i>	Datacon 8800 FC QUANTUM <i>advX</i>
Accuracy	5 µm @ 3s	5 µm @ 3s	4 µm @ 3s	4 µm @ 3s 3 µm @ 3s (option)
Strips, Boats, Panels	8" (200) mm	8" (200) mm	8" (200) mm	8" (200) mm
C2W	8"	8"	8"	8"
UPH (Various Packages)	up to 6,500	up to 10,000	up to 16,000	up to 10,000
Die Size	0.5 - 30 mm	0.5 - 20 mm	1 - 14 mm	0.3 - 40 mm
Crystal Dipping	-	up to 10 mm	-	up to 20 mm
Needle Height Determination	Manual	Manual	Manual	Auto

New!